

1/13

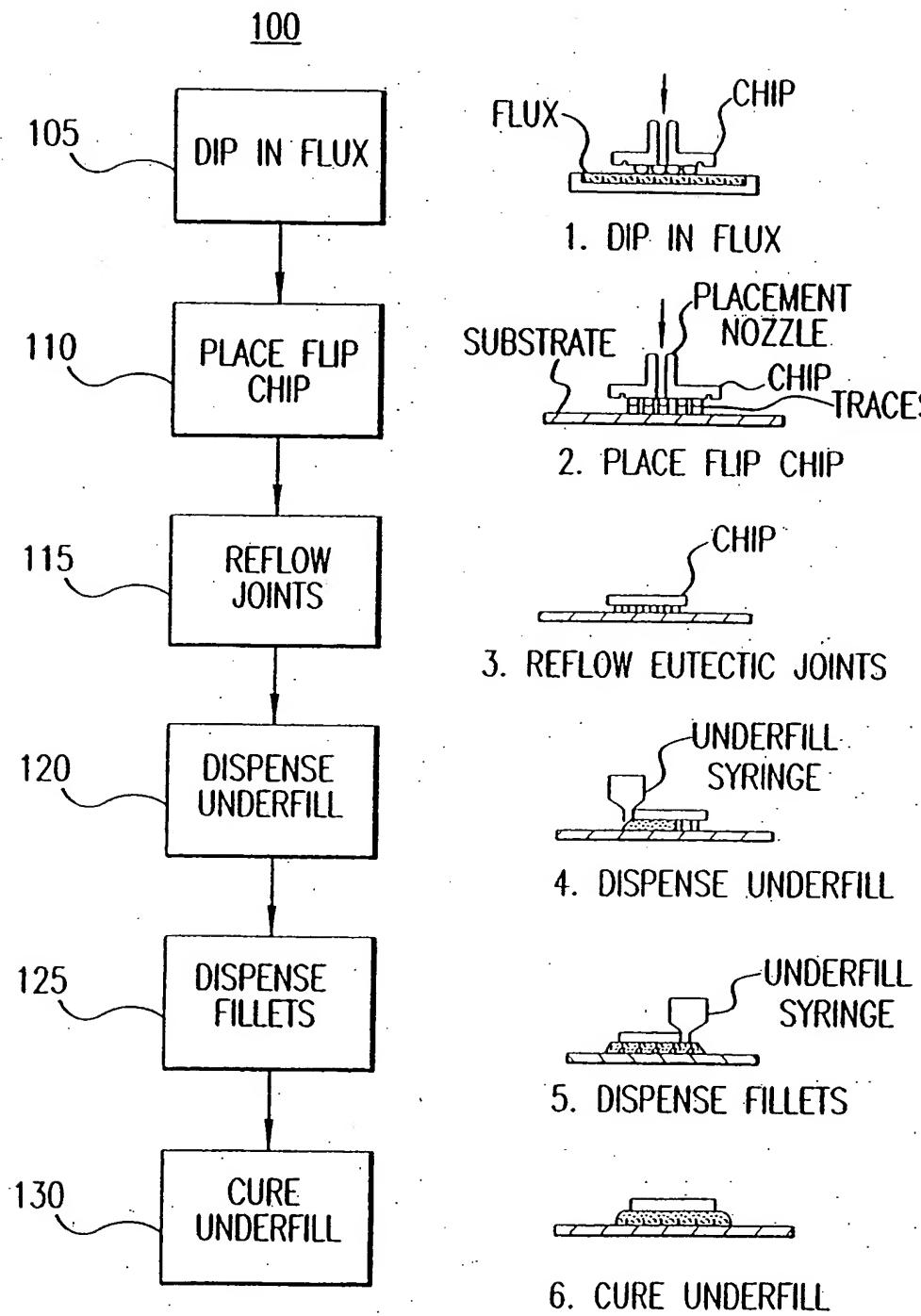


FIG. 1
(Prior Art)

Amendment Dated: April 11, 2005

Reply to Office Action Dated: January 11, 2005

REPLACEMENT SHEET

200

2/13

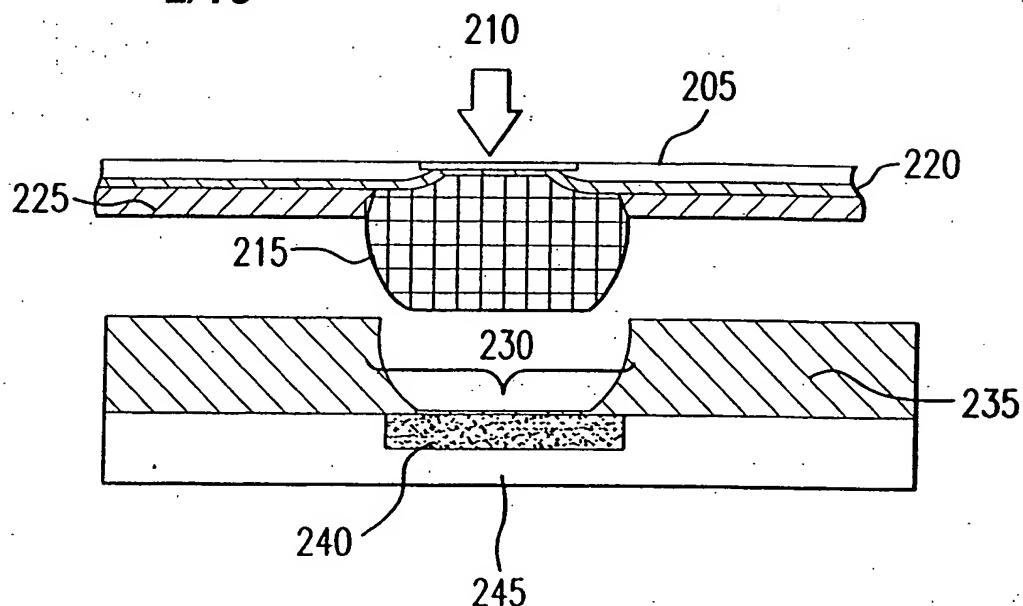


FIG. 2

300

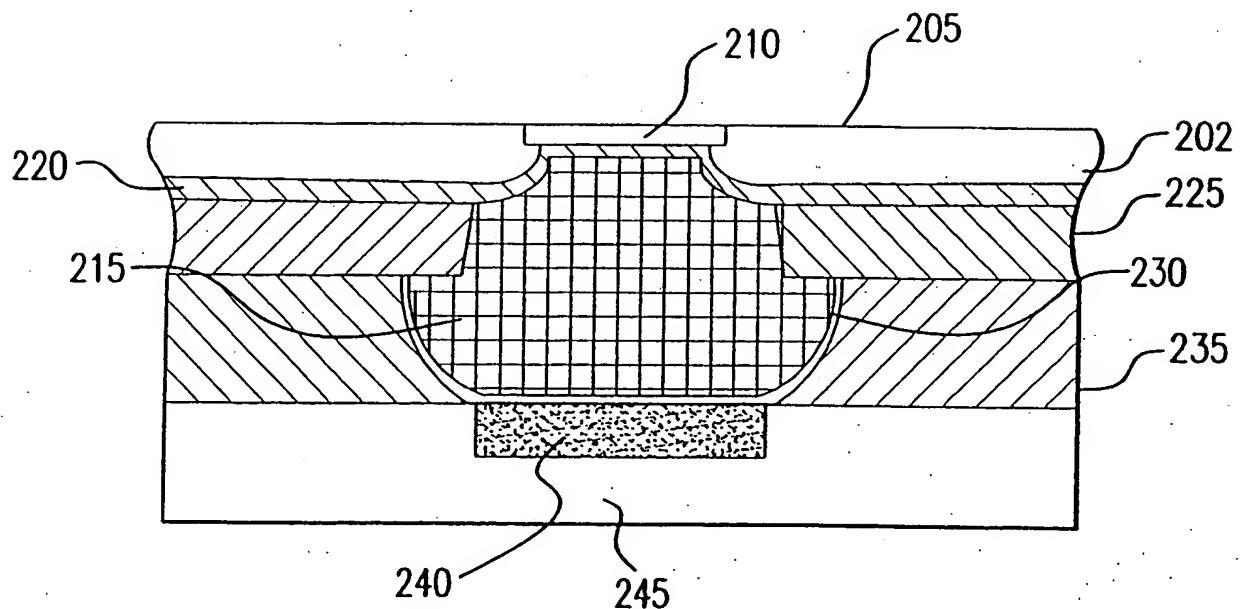


FIG. 3

Application No. 10/612,804
Amendment Dated: April 11, 2005
Reply to Office Action Dated: January 11, 2005
REPLACEMENT SHEET

3/13

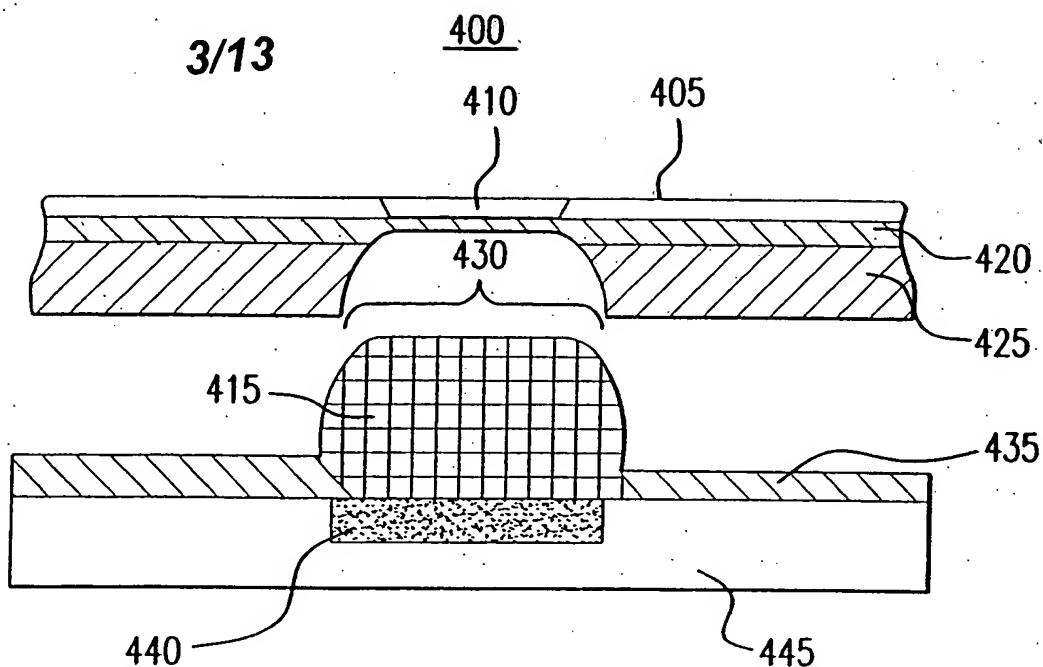


FIG. 4

500

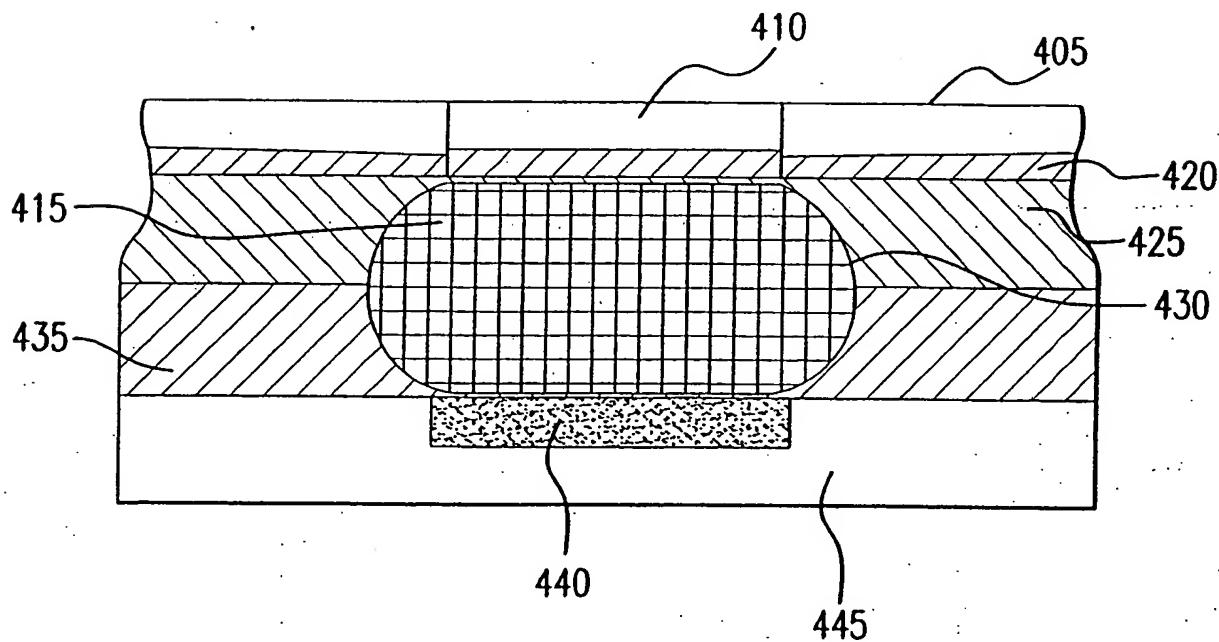


FIG. 5

Application No. 10/612,804
Amendment Dated: April 11, 2005
Reply to Office Action Dated: January 11, 2005
REPLACEMENT SHEET

4/13

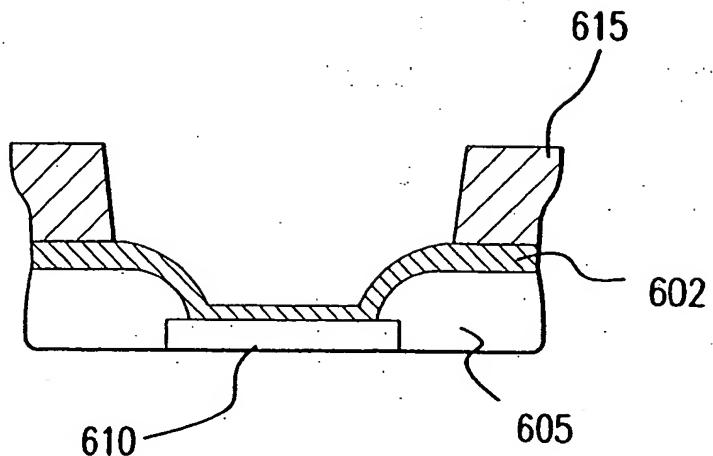


FIG. 6

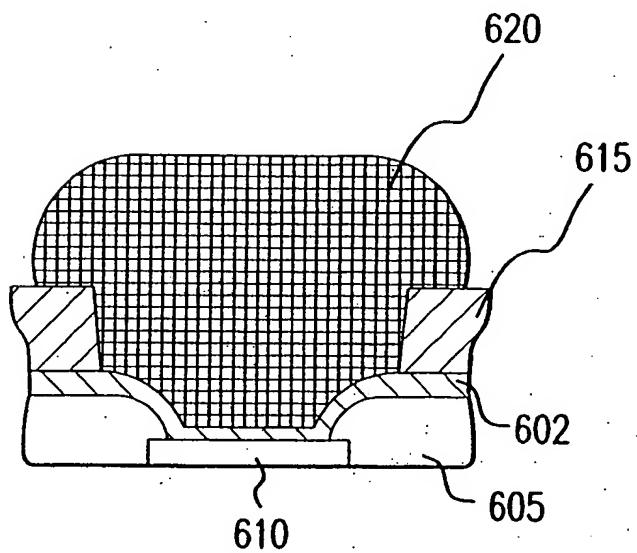


FIG. 7

Application No. 10/612,804

Amendment Dated: April 11, 2005

Reply to Office Action Dated: January 11, 2005

REPLACEMENT SHEET

5/13

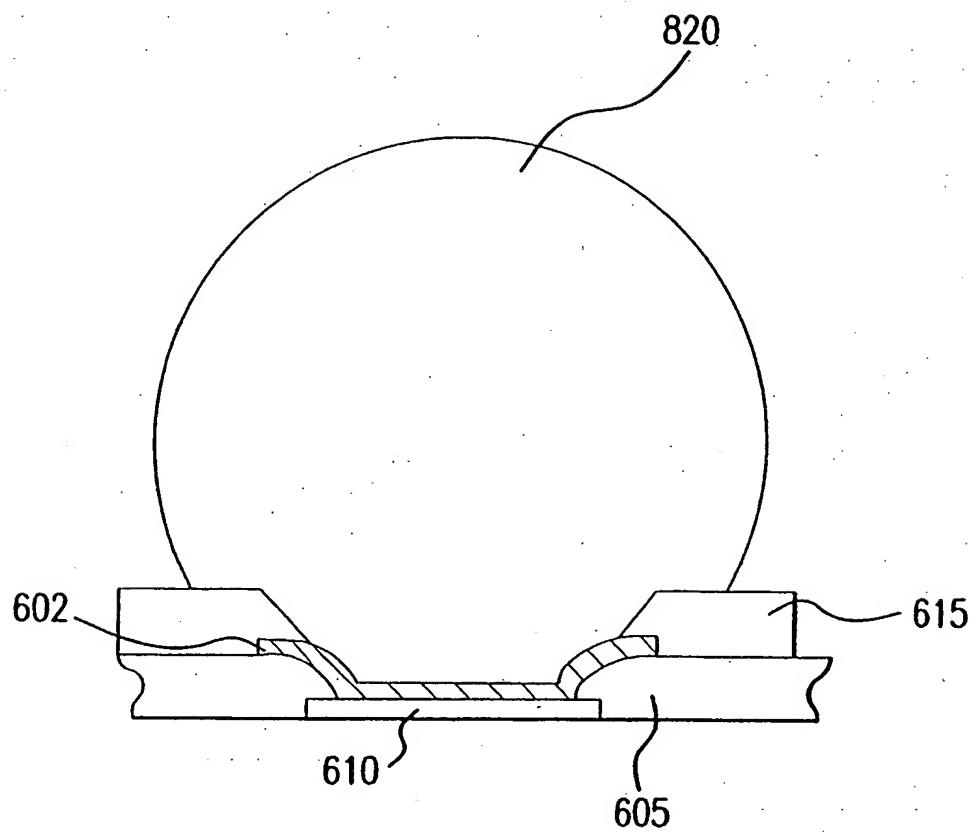


FIG.8

Application No. 10/612,804

Amendment Dated: April 11, 2005

Reply to Office Action Dated: January 11, 2005

REPLACEMENT SHEET

6/13

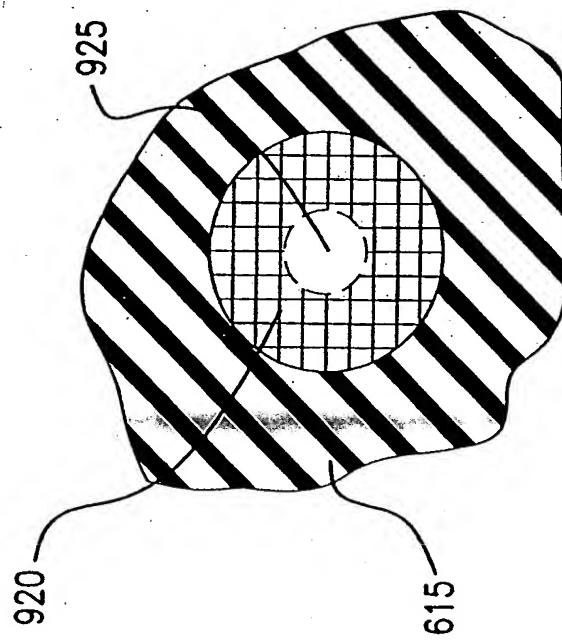


FIG. 9B

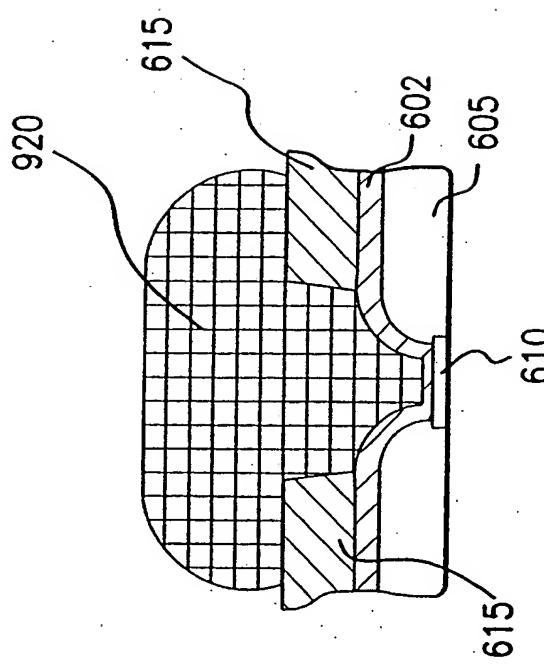


FIG. 9A

7/13

601

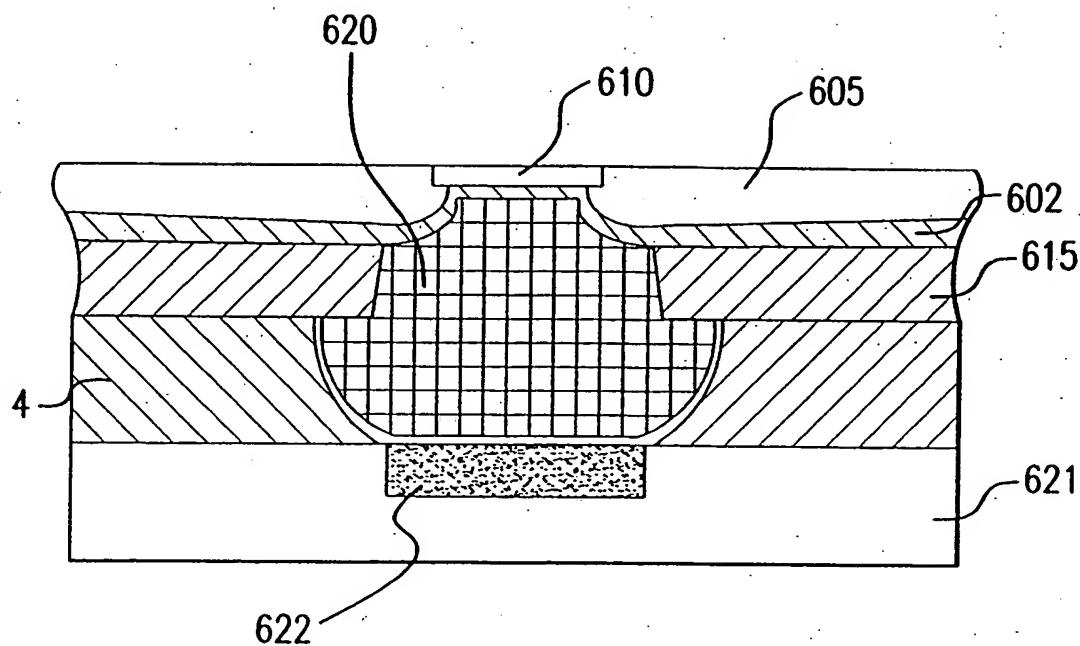


FIG.10

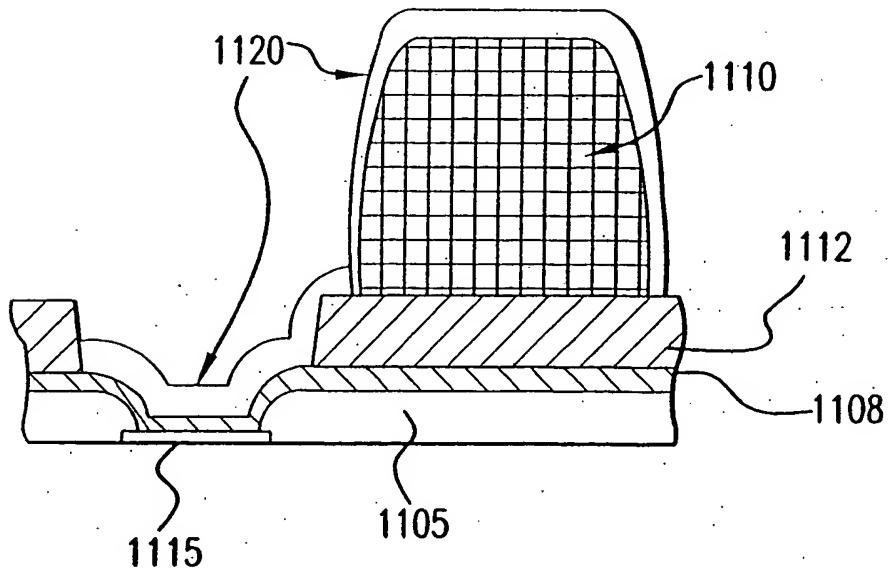


FIG.11

Application No. 10/612,804

Amendment Dated: April 11, 2005

Reply to Office Action Dated: January 11, 2005

REPLACEMENT SHEET

8/13

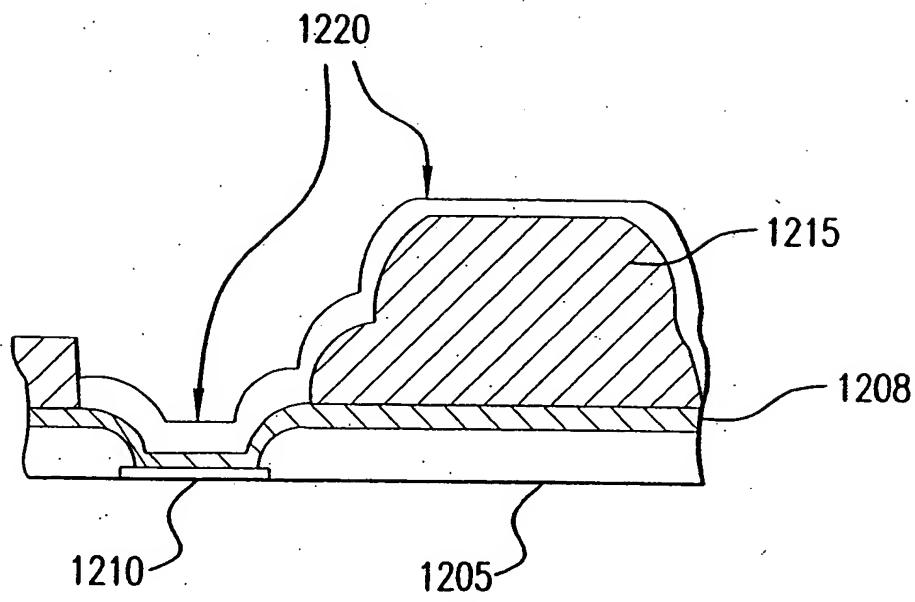


FIG. 12A

9/13

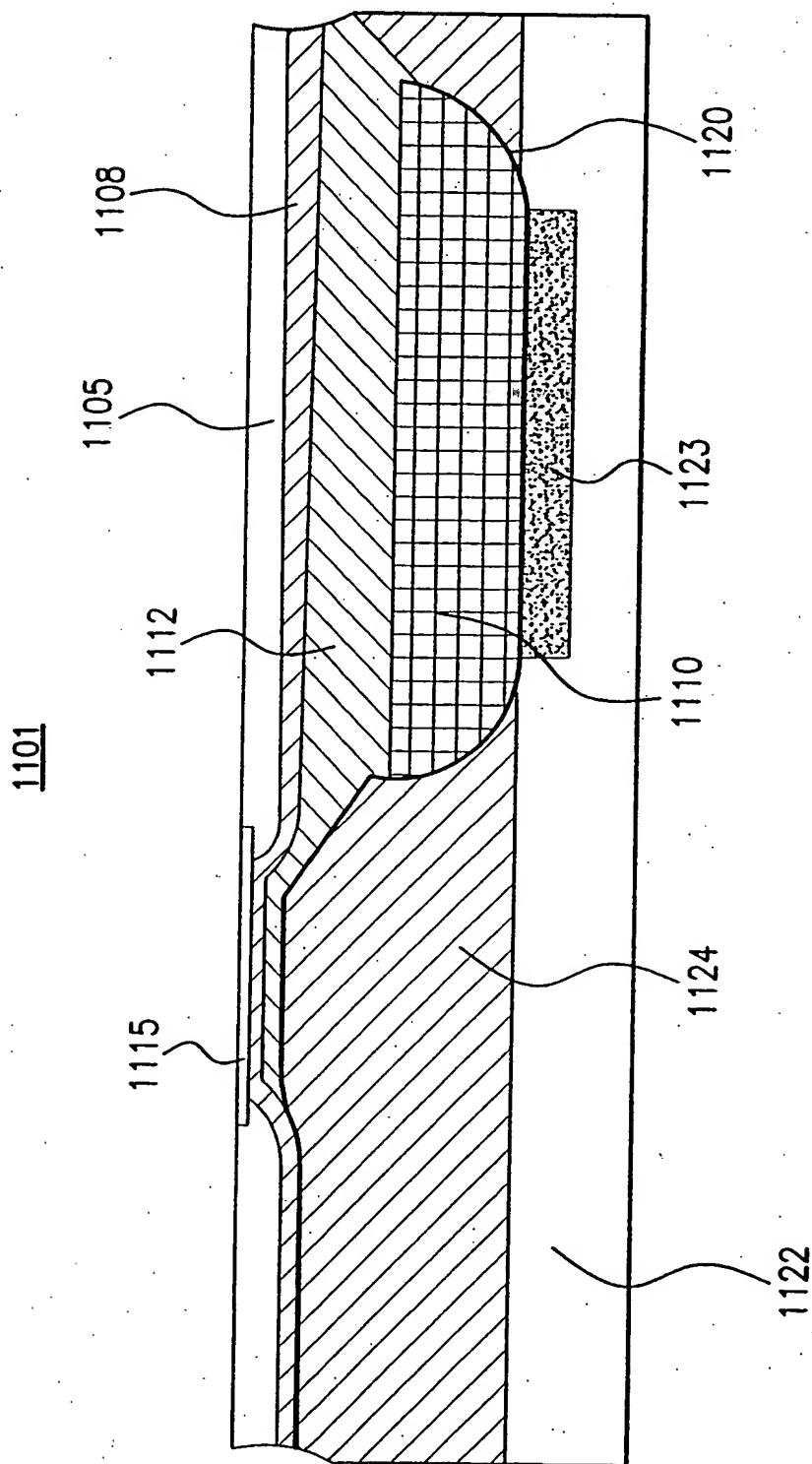
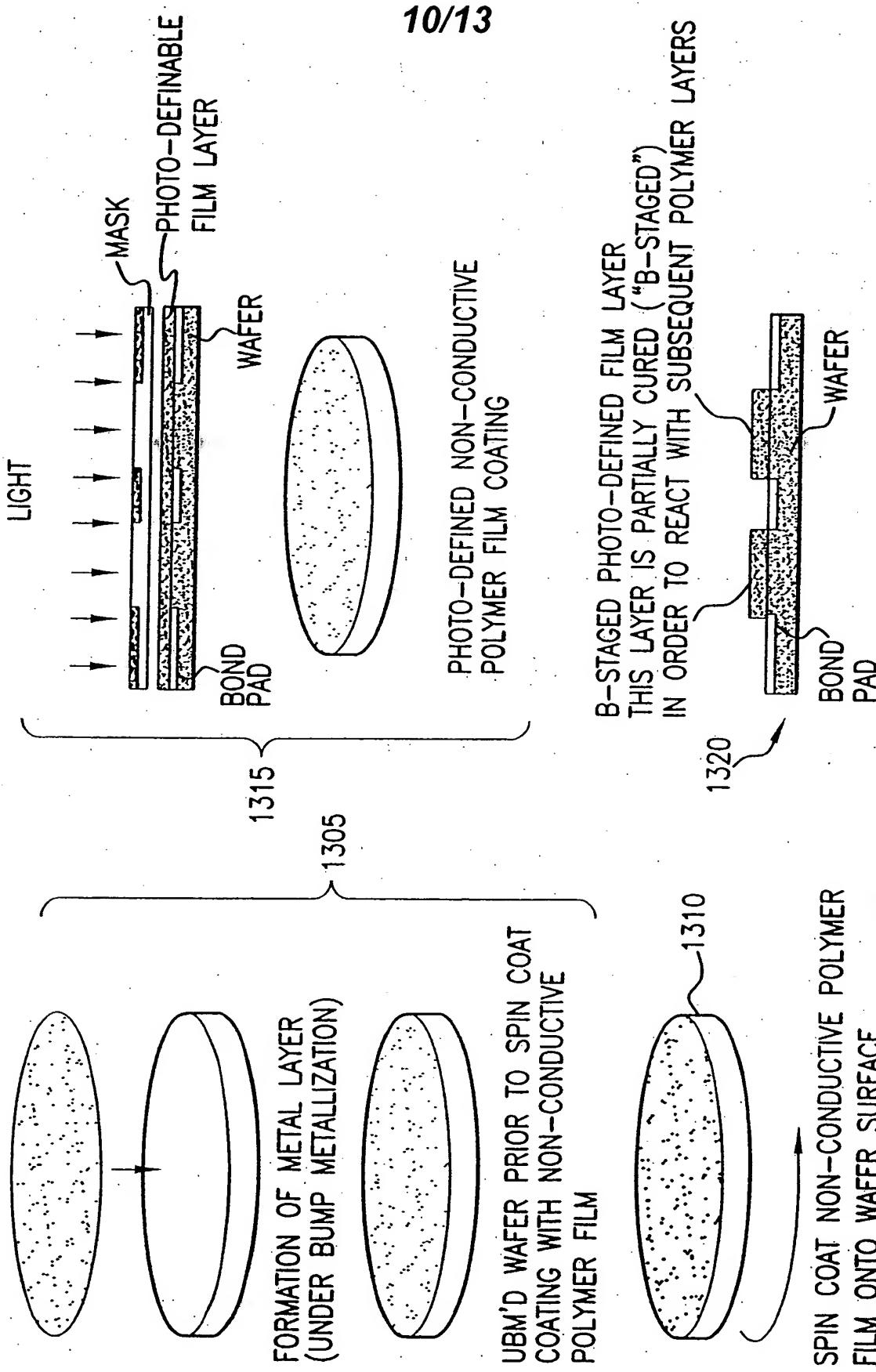


FIG. 12B

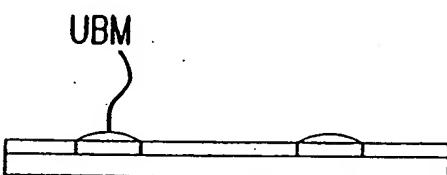
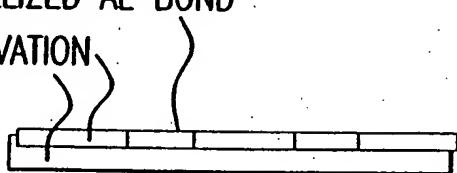
REPLACEMENT SHEET

10/13

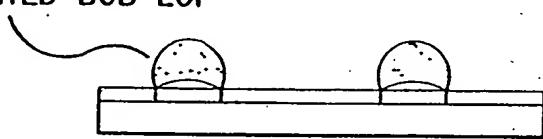


11/13

METALLIZED AL BOND
PASSIVATION



PRINTED BCB ECP



CURED OR B-STAGED BCB ECP



1405

SILICON WAFER

1408

UNDER BUMP
METALLIZATION

1410

POLYMER
BUMP PRINT

1415

CURE OR B-STAGE

1420

DICING

FIG.14A

12/13

1412

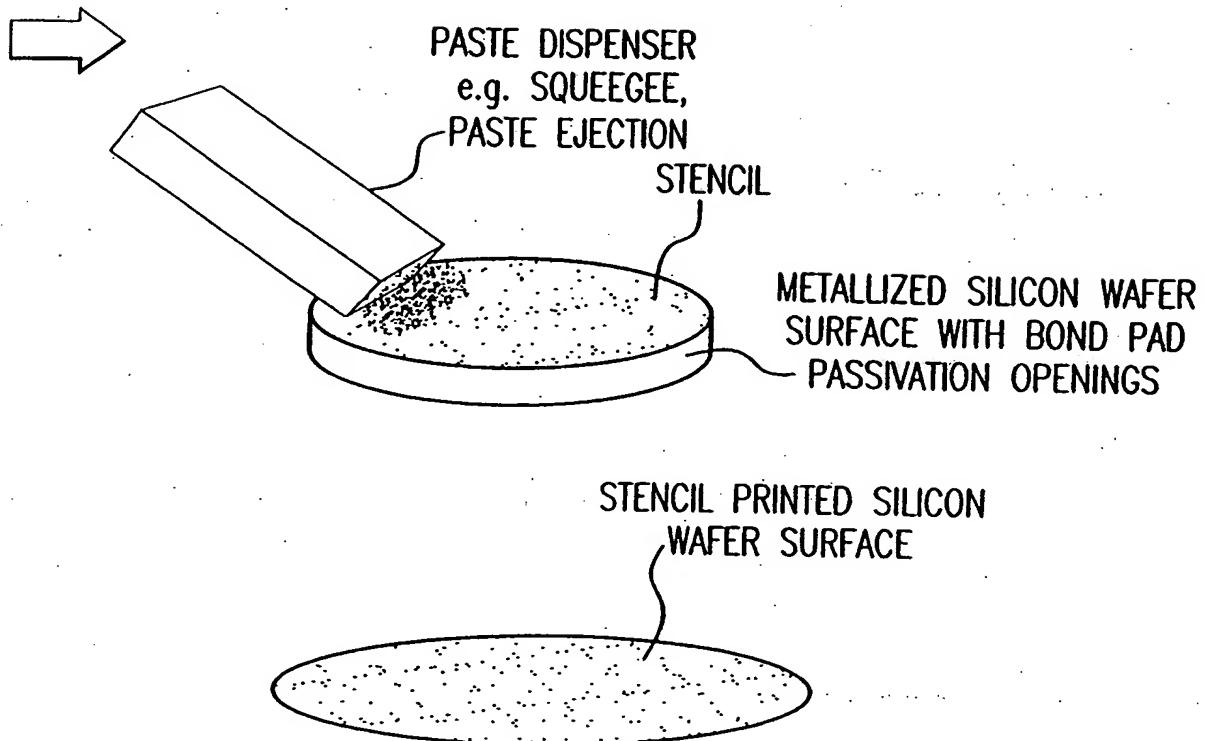


FIG. 14B

1500

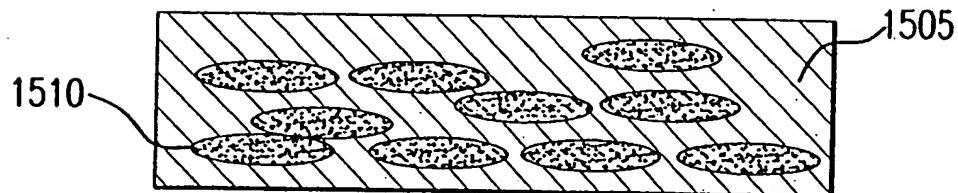


FIG. 15

Application No. 10/612,804

Amendment Dated: April 11, 2005

Reply to Office Action Dated: January 11, 2005

REPLACEMENT SHEET

13/13

1600

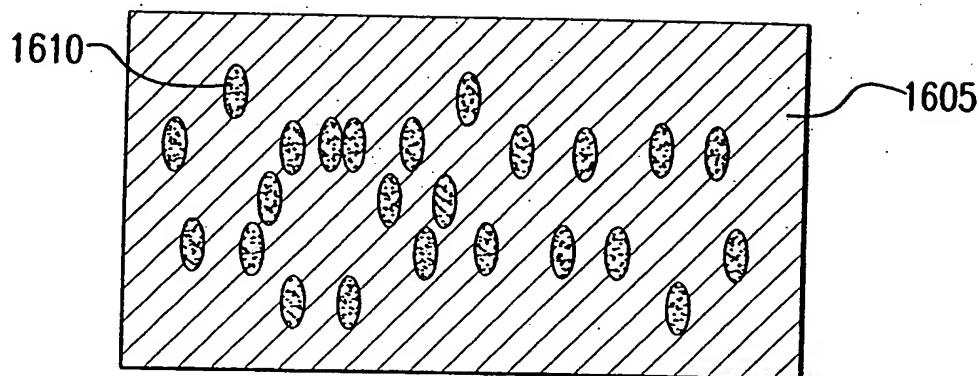


FIG. 16

1700

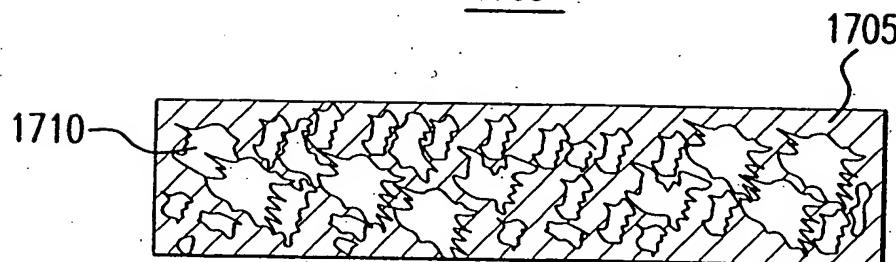


FIG. 17